



Title of Change:	KYEK Iflex tester transfer from Hsinchu to Chunan.	
Proposed first ship date:	24 March 2020	
Contact information:	Contact your local ON Semiconductor Sales Office or ivo.rotthier@onsemi.com>	
Samples:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Type of notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.	
Change Part Identification:	Affected products will be identified with date code and lot history.	
Change Category:	<input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input checked="" type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input checked="" type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____	
Sites Affected:	ON Semiconductor Sites: None	External Foundry/Subcon Sites: KYEK
Description and Purpose:		
	Before Change Description	After Change Description
Test site IFLEX WS1 insertion	KYEK Hsinchu	KYEK Chunan
Bake 1 site		
Test site IFLEX WS2 insertion		
Bake 2 site		
There is no product marking change as a result of this change.		



Qualification Plan:

The internal ON Semiconductor procedure for this type of change will be used.

This involves:

- 2 units will be tested on both sites 30x looped and the result compared.
- 1 wafer will be fully tested of yield comparison.

Electrical Characteristic Summary:

Estimated date for qualification completion: 4 November 2019

List of Affected Standard Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
NCH-RSL10-101Q48-ABG	0W702-005-SW1
NCH-RSL10-101WC51-ABG	0W702-005-SW1

Appendix A: Changed Products

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Product	Customer Part Number	Qualification Vehicle
NCH-RSL10-101Q48-ABG		0W702-005-SW1
NCH-RSL10-101WC51-ABG		0W702-005-SW1